

# **ABSTRACT OF THE DISCLOSURE**

The present invention comprises a first main face (22a) on a surface side of a substrate (21a). An island portion (26) is formed on the first main face (22a) and a semiconductor chip (29), etc. are adhered thereto. The semiconductor chip (29), etc. are sealed in the hollow portion that is constructed by a column portion (23) and a transparent glass plate (36). Then, the column portion (23) and the transparent glass plate (36) are adhered by epoxy resin, or the like.